

Figure 1. 16-Lead Pinout (Top View)

## **PIN NAMES**

Pins	Function
10n	Source 0 Data Inputs
11n	Source 1 Data Inputs
E	Enable Input
S	Select Input
Zn	Outputs

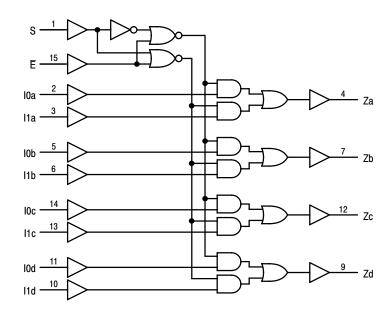


Figure 2. Logic Diagram

## **TRUTH TABLE**

	Inputs			Outputs
Ē	S	I0n	l1n	Zn
H L L	X H H L	X X X L H	X L H X	ITITI

H = High Voltage Level; L = Low Voltage Level; X = High or Low Voltage Level; For I<sub>CC</sub> Reasons DO NOT FLOAT Inputs

## **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Condition	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	$-0.5 \le V_1 \le +7.0$		V
Vo	DC Output Voltage	$-0.5 \le V_{O} \le V_{CC} + 0.5$	Note 1	V
I <sub>IK</sub>	DC Input Diode Current	-50	V <sub>I</sub> < GND	mA
I <sub>OK</sub>	DC Output Diode Current	-50	V <sub>O</sub> < GND	mA
		+50	$V_{O} > V_{CC}$	mA
I <sub>O</sub>	DC Output Source/Sink Current	±50		mA
I <sub>CC</sub>	DC Supply Current Per Supply Pin	±100		mA
I <sub>GND</sub>	DC Ground Current Per Ground Pin	±100		mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150		°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Output in HIGH or LOW State. I<sub>O</sub> absolute maximum rating must be observed.

## **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Тур	Max	Unit
V <sub>CC</sub>	Supply Voltage Operating Data Retention Only	2.0 1.5	3.3 3.3	3.6 3.6	V
VI	Input Voltage	0		5.5	V
Vo	Output Voltage (HIGH or LOW State)	0		V <sub>CC</sub>	V
I <sub>OH</sub>	HIGH Level Output Current, V <sub>CC</sub> = 3.0 V – 3.6 V			-24	mA
I <sub>OL</sub>	LOW Level Output Current, V <sub>CC</sub> = 3.0 V – 3.6 V			24	mA
I <sub>OH</sub>	HIGH Level Output Current, $V_{CC} = 2.7 \text{ V} - 3.0 \text{ V}$			-12	mA
I <sub>OL</sub>	LOW Level Output Current, V <sub>CC</sub> = 2.7 V - 3.0 V			12	mA
T <sub>A</sub>	Operating Free–Air Temperature	-40		+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate, $\rm V_{IN}$ from 0.8 V to 2.0 V, $\rm V_{CC} = 3.0~V$	0		10	ns/V

# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74LCX157DR2	SOIC-16	2500 Tape & Reel
MC74LCX157DR2G	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC74LCX157DT	TSSOP-16*	96 Units / Rail
MC74LCX157DTR2	TSSOP-16*	2500 Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>This package is inherently Pb-Free.

## DC ELECTRICAL CHARACTERISTICS

			T <sub>A</sub> = −40°C	to +85°C	
Symbol	Characteristic	Condition	Min	Max	Unit
V <sub>IH</sub>	HIGH Level Input Voltage (Note 2)	2.7 V ≤ V <sub>CC</sub> ≤ 3.6 V	2.0		V
V <sub>IL</sub>	LOW Level Input Voltage (Note 2)	2.7 V ≤ V <sub>CC</sub> ≤ 3.6 V		0.8	V
V <sub>OH</sub>	HIGH Level Output Voltage	$2.7 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OH} = -100 \mu\text{A}$	V <sub>CC</sub> - 0.2		V
		V <sub>CC</sub> = 2.7 V; I <sub>OH</sub> = -12 mA	2.2		
		V <sub>CC</sub> = 3.0 V; I <sub>OH</sub> = -18 mA	2.4		
		V <sub>CC</sub> = 3.0 V; I <sub>OH</sub> = -24 mA	2.2		
V <sub>OL</sub>	LOW Level Output Voltage	$2.7 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OL} = 100 \mu\text{A}$		0.2	V
		V <sub>CC</sub> = 2.7 V; I <sub>OL</sub> = 12 mA		0.4	
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 16 mA		0.4	
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 24 mA		0.55	
II	Input Leakage Current	$2.7 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; 0 \text{ V} \le \text{V}_{I} \le 5.5 \text{ V}$		±5.0	μΑ
I <sub>CC</sub>	Quiescent Supply Current	$2.7 \le V_{CC} \le 3.6 \text{ V}; V_I = \text{GND or } V_{CC}$		10	μΑ
		2.7 ≤ V <sub>CC</sub> ≤ 3.6 V; 3.6 ≤ V <sub>I</sub> ≤ 5.5 V		±10	μΑ
$\Delta I_{CC}$	Increase in I <sub>CC</sub> per Input	$2.7 \le V_{CC} \le 3.6 \text{ V}; V_{IH} = V_{CC} - 0.6 \text{ V}$		500	μΑ

<sup>2.</sup> These values of  $V_I$  are used to test DC electrical characteristics only.

## AC CHARACTERISTICS ( $t_R = t_F = 2.5 \text{ ns}$ ; $C_L = 50 \text{ pF}$ ; $R_L = 500 \Omega$ )

			T <sub>A</sub>			
			V <sub>CC</sub> = 3.0	V to 3.6 V	V <sub>CC</sub> = 2.7 V	
Symbol	Parameter	Waveform	Min	Max	Max	Unit
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay In to Zn	1	1.5 1.5	5.8 5.8	6.3 6.3	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay S to Zn	1,2	1.5 1.5	7.0 7.0	8.0 8.0	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay E to Zn	2	1.5 1.5	7.0 7.0	8.0 8.0	ns
toshl toslh	Output-to-Output Skew (Note 3)			1.0 1.0		ns

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

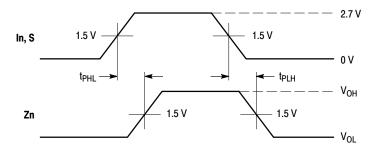
#### **DYNAMIC SWITCHING CHARACTERISTICS**

			T <sub>A</sub> = +25°C			
Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V <sub>OLP</sub>	Dynamic LOW Peak Voltage (Note 4)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$		0.8		V
V <sub>OLV</sub>	Dynamic LOW Valley Voltage (Note 4)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$		8.0		V

<sup>4.</sup> Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

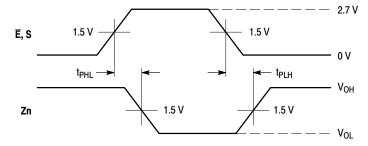
#### **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Parameter Condition		Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	7	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 3.3 \text{ V}, V_{I} = 0 \text{ V or } V_{CC}$	8	pF
C <sub>PD</sub>	Power Dissipation Capacitance	10 MHz, $V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	25	pF



## **WAVEFORM 1 - NON-INVERTING PROPAGATION DELAYS**

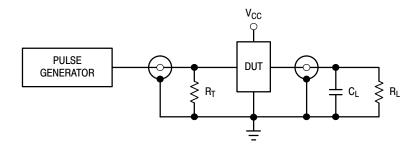
 $t_R$  =  $t_F$  = 2.5 ns, 10% to 90%; f = 1 MHz;  $t_W$  = 500 ns



# WAVEFORM 2 - INVERTING PROPAGATION DELAYS

 $t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$ 

Figure 3. AC Waveforms

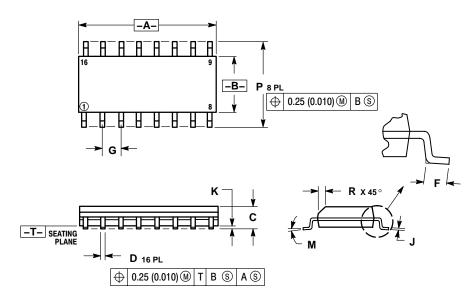


 $C_L=50 pF$  or equivalent (Includes jig and probe capacitance)  $R_L=R_1=500\Omega$  or equivalent  $R_T=Z_{OUT}$  of pulse generator (typically  $50\Omega)$ 

Figure 4. Test Circuit

#### PACKAGE DIMENSIONS

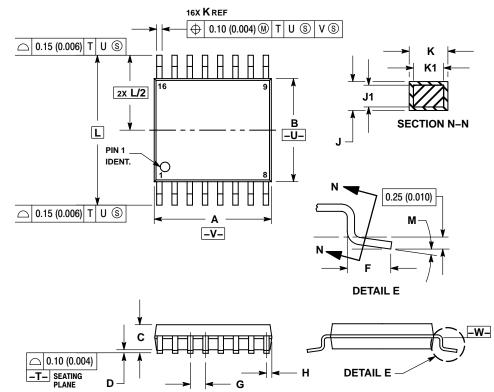
## SOIC-16 **D SUFFIX** CASE 751B-05 **ISSUE J**



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 114.3M, 1982.
  CONTROLLING DIMENSION: MILLIMETER.
  DIMENSIONS A AND B DO NOT INCLUDE
  MOLD PROTRUSION.
  MAXIMUM MOLD PROTRUSION 0.15 (0.006)
  DED SIDE.
- PER SIDE.
  DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION SHALL BE 0.127 (0.005) TOTAL
  IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
М	0 °	7°	0°	7°
Р	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

## TSSOP-16 **DT SUFFIX** CASE 948F-01 **ISSUE O**



- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A DOES NOT INCLUDE MOLD FLASH.
  PROTRUSIONS OR GATE BURRS. MOLD FLASH
  OR GATE BURRS SHALL NOT EXCEED 0.15
- (0.006) PER SIDE.

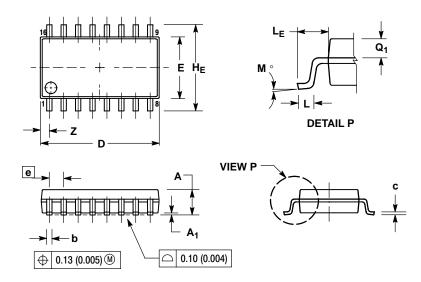
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. DIMENSION K DOES NOT INCLUDE DAMBAR
- PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION. SHALL BE 0.08 (0.003) TOTAL IN
  EXCESS OF THE K DIMENSION AT MAXIMUM
  MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026	BSC
Н	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40		0.252 BSC	
M	0°	8°	0°	8 °

## **PACKAGE DIMENSIONS**

SOEIAJ-16 **M SUFFIX** CASE 966-01 **ISSUE O** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	-	2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050	BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
М	0 °	10°	0 °	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z		0.78		0.031

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